2SA564, 2SA564A

Silicon PNP Epitaxial Planar Type

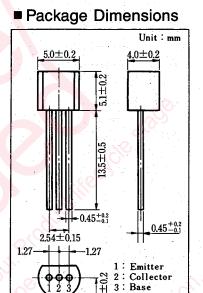
For general amplification

Features

•Large DC current gain h_{FE}

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Item		Symbol	Value	Unit	
Collector-Base Voltage	2SA564	V _{CBO}	-25	V	
	2SA564A	♥ сво	-45	V,	
Collector-Emitter Voltage	2SA564	V	-25	· V	
	2SA564A	V _{CEO}	-45		
Emitter-Base Voltage		V _{EBO}	7	No. No.	
Peak Collector Voltage		I _{CP}	-200	mA	
Collector Current		Ic	-100	mA	
Collector Power Dissipation		Pc	400	mW	
Junction Temperature		Tj	150	C	
Storage Temperature		T _{stg}	-55~+150	Ċ	

Absolute Maximum Ratings (Ta=25°C)



JEDEC : TO-92 EIAJ : SC-43

Electrical Characteristics (Ta=25°C)

Item		Symbol	Condition	min.	typ.	max.	Unit
Collector Cutoff Current		I _{сво}	$V_{CB} = -20 \text{ V}, I_E = 0$			-1	
		I _{ceo}	$V_{ce} = -20 V, I_B = 0$		No.	-10	μA
Collector-Base	ollector-Base 2SA564	- V _{CBO}	$I_{c} = -10 \mu A$, $I_{E} = 0$	-25	2		v
Voltage	2SA564A			-45			
Collector-Emitter Voltage	2SA564	V _{CEO}	$I_c = -2 \text{ mA}, I_B = 0$	-25			v
	2SA564A			-45			
Emitter-Base Voltage		Vebo	$I_{\rm E} = -10 \ \mu {\rm A}, \ I_{\rm C} = 0$	-7			v
DC Current Gain		h _{FE} *	$V_{ce} = -5 V, I_c = -2 mA$	130		520	
Collector-Emitter Saturation Voltage VCE(se		V _{CE(sat)}	$I_c = -50 \text{ mA}, I_B = -2.5 \text{ mA}$			-1	V .
Transition Frequency f _T		fT	$V_{CB} = -10V, I_E = 2mA, f = 200MHz$		150		MHz
Collector Output Capacitance Cob		Cob	$V_{cB} = -10 V$, $I_E = 0$, $f = 1 MHz$		3.5		pF

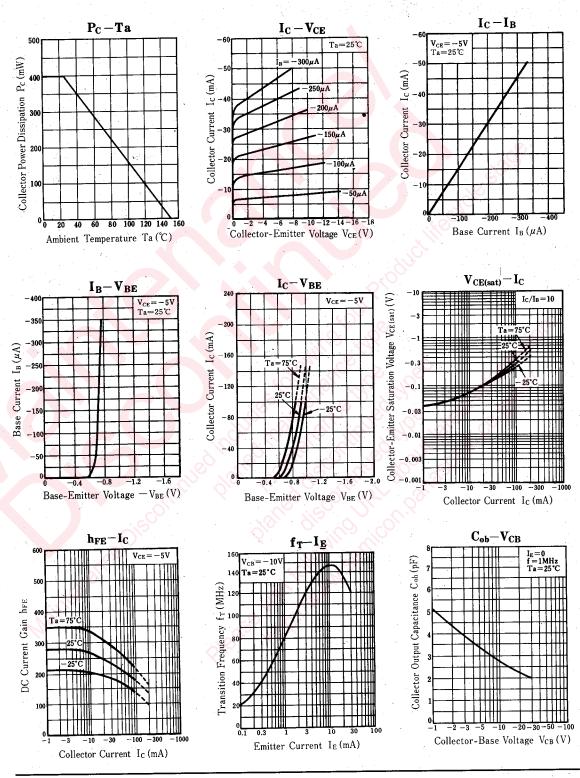
-101 -

* h_{FE} Ranking

Rank	Q	R	S
h _{FE}	130~260	180~360	260~520

Transistors

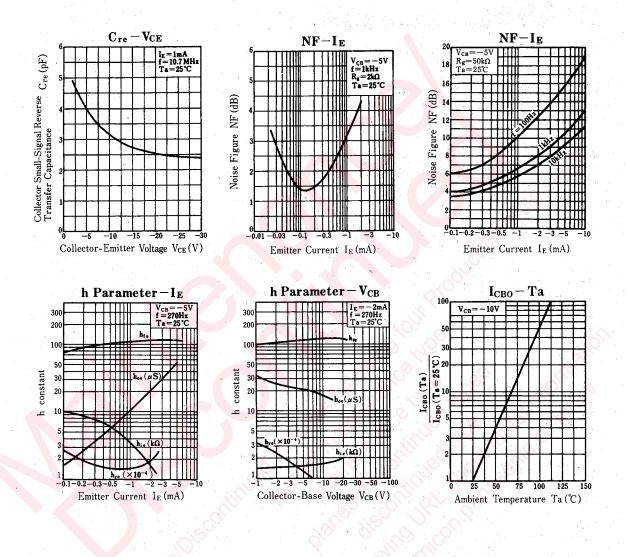
2SA564, 2SA564A



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-102-

Transistors



— 103 —

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